

Product Information

Lead-free HASL refill alloy FELDER-ISO-Tin® „HAL-Sn100Ni+Refill“

Lead-free refill solder for hot air solder leveling units, RoHS conformity acc. 2011/65/EU
Sn99,9NiGe acc. to Fuji-Pat. No. DE19816671C2, US6179.935, JP3296289

Item-No.: 5512911026

All information about our products is the result of our long standing experience which we would like to pass on to our customers as application support. However, as we do not have any influence on the application of the works carried out with our products, please see the warranty claims in our conditions of sale because our liability is limited.

This product information does not constitute warranted properties.

Application

In order to compensate the entry of copper into “HAL-Sn100Ni+” in hot air solder levelling units we recommend “HAL-Sn100Ni+ Refill”. Hereto a regular control of the solder bath is unavoidable.

Properties

Beside the well-known advantages of Ni-endowed solder our alloy reaches improved wetting qualities and **lowest dross formation** in comparison to all other lead-free solder by the adding of Germanium. For the HAL-application the Ni-endowment was optimized accordingly.

In fact Sn100Ni+ has a lower Cu leaching quote than other lead-free solder, nevertheless a copper level compensation is necessary.

Alloy: Sn99,9NiGe
 Melting point: 232 °C (reduces in the solder bath to 227 °C!)

Impurities / Tolerances

Sn100Ni+

Element	Ag	Al	As	Bi	Cd	Cu	Fe
content (%)	0,003	0,001	0,03	0,06	0,002	< 0,05	0,02
Element	Ge		Ni	Pb	Sb	Sn	Zn
content (%)	0,01 - 0,015		0,12±0,02	0,05	0,1	Rest	0,001

Delivery Forms

400 g - rods, 330 x 20 x 10 mm,

Other alloys are included in our standard delivery program.

Storage

Stored at constant indoor climate durable for an unlimited period!